

Astek Corporation
P/N: 70-922300-B

		Before Press	After Press	
PADS				
N7205-2		0.0006	0.0021	1/2 OZ + PLATING
GND				
		0.028	0.028	POLY
		0.0006	0.0006	1/2 OZ CU
N7305-2		0.0033	0.0028	1080 PREPREG
N7305-2		0.0033	0.0028	1080 PREPREG
PWR				
N7205-2		0.0006	0.0006	1/2 OZ CU
PADS				
		0.028	0.028	POLY
		0.0006	0.0021	1/2 OZ + PLATING
		0.065	Thickness Before Lamination	
		0.067	Thickness Out Of Lamination	
		0.0591	Minimum allowable thickness (corresponds to 1.5 mm)	

NOTES:

1. PCB SHALL BE FABRICATED TO IPC-6011 AND 6012 CLASS 2 OR BETTER
2. MATERIAL AS DEFINED IN STACK-UP DRAWING
3. FINISHED THICKNESS: 0.067 +/-0.007"
4. FINISH: 30 MICRO INCH GOLD PLATING OVER 50 MICRO INCH NICKEL UNDERPLATE
5. SOLDER MASK: GREEN LPI PER IPC-SM-840-C, CLASS T
SIDES: TOP AND BOTTOM
6. SILKSCREEN: NON-CONDUCTIVE WHITE EPOXY BASED INK; NOT ALLOWED ON COMPONENT PADS OR IN MOUNTING HOLES.
7. ALL HOLES ARE VIA-IN-PAD AND SHALL BE FILLED AND FINISHED
8. 100% TESTING FOR OPENS AND SHORTS REQUIRED.
9. PERFORM GERBER FILE DATABASE DESIGN RULE CHECK.
10. VENDOR MAY ALTER PHOTO DATA (GERBER) TO COMPENSATE FOR ETCHING PROCESS
11. SOLDERABILITY TEST, CATEGORY 2 OF J-STD-003 OR STRESSED MICROSECTION

		Astek Corporation 5055 Corporate Plaza Drive Colorado Springs, CO 80919 © Copyright 2012 Astek Corporation All rights reserved	
ENGINEER: Steve Wint			
PART:		70-922300	REV B
DATE: 1/21/2012		SHEET 1	OF 1